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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	M32C/80
Core Size	16/32-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	121
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	31K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 34x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LFQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30835fjgp-u5

1. Overview

The M32C/83 Group (M32C/83, M32C/83T) microcomputer is a single-chip control unit that utilizes high-performance silicon gate CMOS technology with the M32C/80 Series CPU core. The M32C/83 Group (M32C/83, M32C/83T) is available in 144-pin and 100-pin plastic molded LQFP/QFP packages.

With a 16-Mbyte address space, this microcomputer combines advanced instruction manipulation capabilities to process complex instructions by less bytes and execute instructions at higher speed.

It includes a multiplier and DMAC adequate for office automation, communication devices and industrial equipments, and other high-speed processing applications.

1.1 Applications

Automobiles, audio, cameras, office equipment, communications equipment, portable equipment, etc.

1.2 Performance Overview

Tables 1.1 and 1.2 list performance overview of the M32C/83 Group (M32C/83, M32C/83T).

Table 1.1 M32C/83 Group (M32C/83, M32C/83T) Performance (144-Pin Package)

Characteristic		Performance	
		M32C/83	M32C/83T
CPU	Basic Instructions	108 instructions	
	Minimum Instruction Execution Time	31.3 ns (f(BCLK)=32 MHz, Vcc=4.2 to 5.5 V) ⁽³⁾ 50 ns (f(BCLK)=20 MHz, Vcc=3.0 to 5.5 V)	31.3 ns (f(BCLK)=32 MHz, Vcc=4.2 to 5.5 V) ⁽³⁾
	Operating Mode	Single-chip mode, Memory expansion mode and Microprocessor mode	Single-chip mode
	Address Space	16 Mbytes	
	Memory Capacity	See Table 1.3	
Peripheral Function	I/O Port	123 I/O pins and 1 input pin	
	Multifunction Timer	Timer A: 16 bits x 5 channels, Timer B: 16 bits x 6 channels Three-phase motor control circuit	
	Intelligent I/O	Time measurement function: 16 bits x 12 channels Waveform generating function: 16 bits x 28 channels Communication function (Clock synchronous serial I/O, Clock asynchronous serial I/O, HDLC data processing, Clock synchronous variable length serial I/O, IEBus ⁽¹⁾ , 8-bit or 16-bit Clock synchronous serial I/O)	
	Serial I/O	5 Channels Clock synchronous serial I/O, Clock asynchronous serial I/O, IEBus ⁽¹⁾ , I ² C bus ⁽²⁾	
	CAN Module	1 channel Supporting CAN 2.0B specification	
	A/D Converter	10-bit A/D converter: 2 circuit, 34 channels	
	D/A Converter	8 bits x 2 channels	
	DMAC	4 channels	
	DMAC II	Can be activated by all peripheral function interrupt sources Immediate transfer, Calculation transfer and Chain transfer functions	
	DRAM	CAS before RAS refresh, Self-refresh, EDO, EP	
	CRC Calculation Circuit	CRC-CCITT	
	X/Y Converter	16 bits x 16 bits	
	Watchdog Timer	15 bits x 1 channel (with prescaler)	
	Interrupt	42 internal and 8 external sources, 5 software sources, Interrupt priority level: 7	
	Clock Generation Circuit	4 circuits Main clock oscillation circuit(*), Sub clock oscillation circuit(*), On-chip oscillator, PLL frequency synthesizer (*)Equipped with a built-in feedback resistor. Ceramic resonator or crystal oscillator must be connected externally	
	Oscillation Stop Detect Function	Main clock oscillation stop detect function	
Electrical Characteristics	Supply Voltage	4.2 to 5.5 V (f(BCLK)=32 MHz) 3.0 to 5.5 V (f(BCLK)=20 MHz, through VDC) 3.0 to 3.6 V (f(BCLK)=20 MHz, not through VDC)	4.2 to 5.5 V (f(BCLK)=32 MHz)
	Power Consumption	41 mA (Vcc=5 V, f(BCLK)=32 MHz) 38 mA (Vcc=5 V, f(BCLK)=30 MHz) 26 mA (Vcc=3.3 V, f(BCLK)=20 MHz) 470 μ A (Vcc=5 V, f(XCIN)=32 kHz, in wait mode) 340 μ A (Vcc=3.3 V, f(XCIN)=32 kHz, through VDC, in wait mode) 5.0 μ A (Vcc=3.3 V, f(XCIN)=32 kHz, not through VDC, in wait mode) 0.4 μ A (Vcc=5 V, stop mode) 0.4 μ A (Vcc=3.3 V, stop mode)	41 mA (Vcc=5 V, f(BCLK)=32 MHz) 38 mA (Vcc=5 V, f(BCLK)=30 MHz) 470 μ A (Vcc=5 V, f(XCIN)=32 kHz, in wait mode) 0.4 μ A (Vcc=5 V, stop mode)
Flash Memory	Program/Erase Supply Voltage	3.3 $\pm$ 0.3 V or 5.0 $\pm$ 0.5 V	5.0 $\pm$ 0.5 V
	Program and Erase Endurance	100 times	
Operating Ambient Temperature		-20 to 85°C, -40 to 85°C (optional)	-40 to 85°C (T version)
Package		144-pin plastic molded LQFP	

NOTES:

1. IEBus is a trademark of NEC Electronics Corporation.
2. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
3. Contact our sales office if 30-MHz or higher frequency is required.

All options are on a request basis.

Table 1.4 Pin Characteristics for 144-Pin Package (Continued)

Pin No	Control Pin	Port	Interrupt Pin	Timer Pin	UART/CAN Pin	Intelligent I/O Pin	Analog Pin	Bus Control Pin ⁽¹⁾
49		P136				OUTC21/ISCLK2		
50		P135				OUTC22/ISRxD2/IEIN		
51		P134				OUTC20/ISTxD2/IEOUT		
52		P57						RDY
53		P56						ALE/RAS
54		P55						HOLD
55		P54						HLDA/ALE
56		P133				OUTC23		
57	Vss							
58		P132				OUTC26		
59	Vcc							
60		P131				OUTC25		
61		P130				OUTC24		
62		P53						CLKOUT/BCLK/ALE
63		P52						RD/DW
64		P51						WRH/BHE/CASH
65		P50						WRL/WR/CASL
66		P127				OUTC37		
67		P126				OUTC36		
68		P125				OUTC35		
69		P47						CS0/A23
70		P46						CS1/A22
71		P45						CS2/A21
72		P44						CS3/A20(MA12)
73		P43						A19(MA11)
74	Vcc							
75		P42						A18(MA10)
76	Vss							
77		P41						A17(MA9)
78		P40						A16(MA8)
79		P37						A15(MA7)/(D15)
80		P36						A14(MA6)/(D14)
81		P35						A13(MA5)/(D13)
82		P34						A12(MA4)/(D12)
83		P33						A11(MA3)/(D11)
84		P32						A10(MA2)/(D10)
85		P31						A9(MA1)/(D9)
86		P124				OUTC34		
87		P123				OUTC33		
88		P122				OUTC32/ISRxD3		
89		P121				OUTC31/ISCLK3		
90		P120				OUTC30/ISTxD3		
91	Vcc							
92		P30						A8(MA0)/(D8)
93	Vss							
94		P27					AN27	A7/(D7)
95		P26					AN26	A6/(D6)
96		P25					AN25	A5/(D5)

NOTES:

1. Bus control pins in M32C/83T cannot be used.

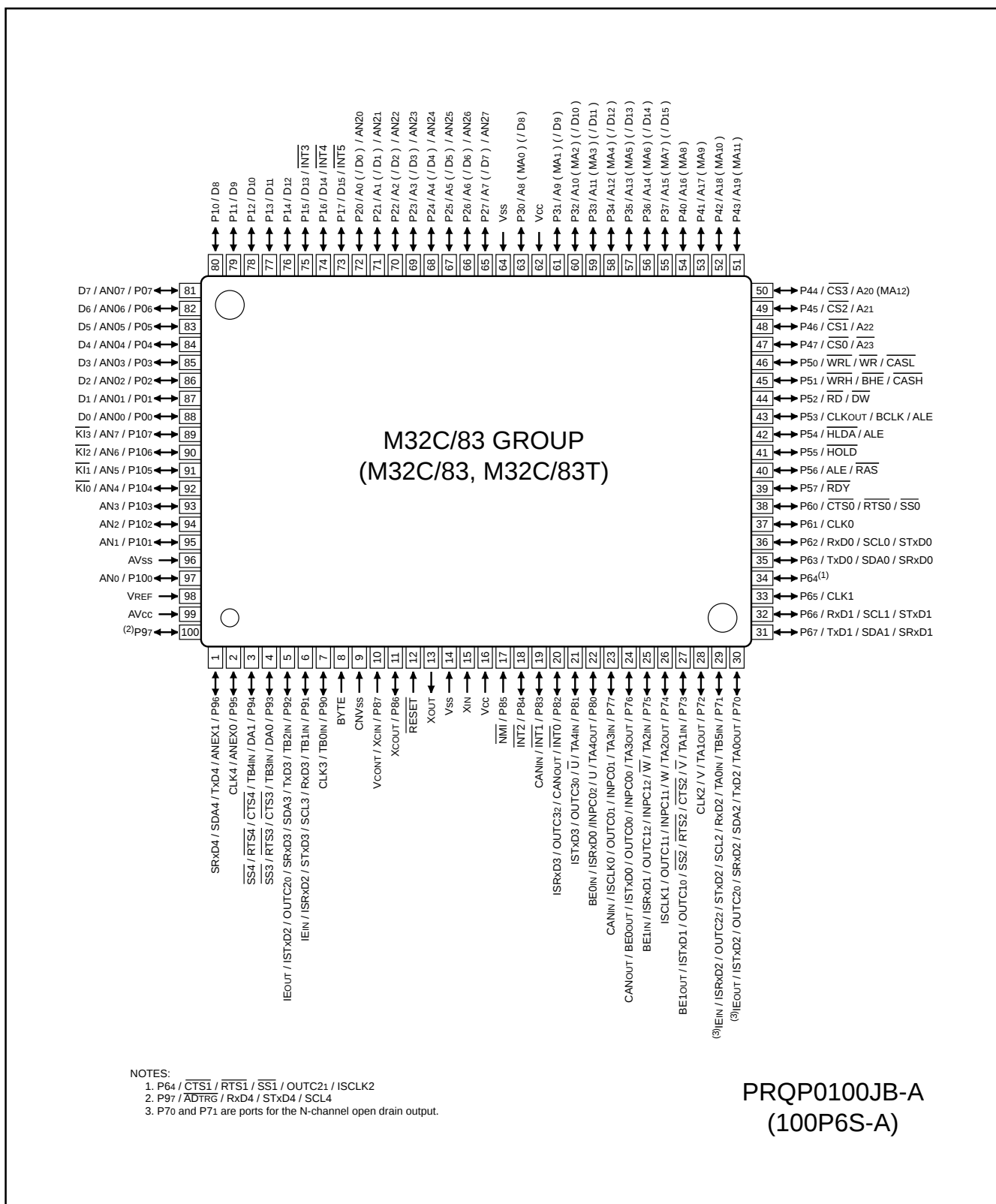


Figure 1.4 Pin Assignment for 100-Pin Package

Table 1.5 Pin Characteristics for 100-Pin Package (Continued)

Package Pin No		Control Pin	Port	Interrupt Pin	Timer Pin	UART/CAN Pin	Intelligent I/O Pin	Analog Pin	Bus Control Pin ⁽¹⁾
FP	GP								
51	49		P43						A19(MA11)
52	50		P42						A18(MA10)
53	51		P41						A17(MA9)
54	52		P40						A16(MA8)
55	53		P37						A15(MA7)/(D15)
56	54		P36						A14(MA6)/(D14)
57	55		P35						A13(MA5)/(D13)
58	56		P34						A12(MA4)/(D12)
59	57		P33						A11(MA3)/(D11)
60	58		P32						A10(MA2)/(D10)
61	59		P31						A9(MA1)/(D9)
62	60	VCC							
63	61		P30						A8(MA0)/(D8)
64	62	VSS							
65	63		P27					AN27	A7(/D7)
66	64		P26					AN26	A6(/D6)
67	65		P25					AN25	A5(/D5)
68	66		P24					AN24	A4(/D4)
69	67		P23					AN23	A3(/D3)
70	68		P22					AN22	A2(/D2)
71	69		P21					AN21	A1(/D1)
72	70		P20					AN20	A0(/D0)
73	71		P17	INT5					D15
74	72		P16	INT4					D14
75	73		P15	INT3					D13
76	74		P14						D12
77	75		P13						D11
78	76		P12						D10
79	77		P11						D9
80	78		P10						D8
81	79		P07					AN07	D7
82	80		P06					AN06	D6
83	81		P05					AN05	D5
84	82		P04					AN04	D4
85	83		P03					AN03	D3
86	84		P02					AN02	D2
87	85		P01					AN01	D1
88	86		P00					AN00	D0
89	87		P107	KI3				AN7	
90	88		P106	KI2				AN6	
91	89		P105	KI1				AN5	
92	90		P104	KI0				AN4	
93	91		P103					AN3	
94	92		P102					AN2	
95	93		P101					AN1	
96	94	AVSS							
97	95		P100					AN0	
98	96	VREF							
99	97	AVCC							
100	98		P97			RxD4/SCL4/STxD4		ADTRG	

NOTES:

1. Bus control pins in M32C/83T cannot be used.

2.1.8.5 Register Bank Select Flag (B)

The register bank 0 is selected when the B flag is set to "0". The register bank 1 is selected when this flag is set to "1".

2.1.8.6 Overflow Flag (O)

The O flag is set to "1" when the result of an arithmetic operation overflows; otherwise "0".

2.1.8.7 Interrupt Enable Flag (I)

The I flag enables a maskable interrupt.

An interrupt is disabled when the I flag is set to "0" and enabled when the I flag is set to "1". The I flag is set to "0" when an interrupt is acknowledged.

2.1.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to "0". USP is selected when this flag is set to "1".

The U flag is set to "0" when a hardware interrupt is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.1.8.9 Processor Interrupt Priority Level (IPL)

IPL, 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has greater priority than IPL, the interrupt is enabled.

2.1.8.10 Reserved Space

When writing to a reserved space, set to "0". When read, its content is indeterminate.

2.2 High-Speed Interrupt Registers

Registers associated with the high-speed interrupt are as follows. Refer to **10.4 High-Speed Interrupt** for details.

- Flag save register (SVF)
- PC save register (SVP)
- Vector register (VCT)

2.3 DMAC-Associated Registers

Registers associated with DMAC are as follows. Refer to **12. DMAC** for details.

- DMA mode register (DMD0, DMD1)
- DMA transfer count register (DCT0, DCT1)
- DMA transfer count reload register (DRC0, DRC1)
- DMA memory address register (DMA0, DMA1)
- DMA SFR address register (DSA0, DSA1)
- DMA memory address reload register (DRA0, DRA1)

3. Memory

Figure 3.1 shows a memory map of the M32C/83 group (M32C/83, M32C/83T).

M32C/83 group (M32C/83, M32C/83T) provides 16-Mbyte address space from addresses 000000₁₆ to FFFFFFF₁₆.

The internal ROM is allocated lower addresses beginning with address FFFFFFF₁₆. For example, a 64-Kbyte internal ROM is allocated addresses FF0000₁₆ to FFFFFFF₁₆.

The fixed interrupt vectors are allocated addresses FFFFDC₁₆ to FFFFFFF₁₆. It stores the starting address of each interrupt routine. Refer to **10. Interrupts** for details.

The internal RAM is allocated higher addresses beginning with address 000400₁₆. For example, a 10-Kbyte internal RAM is allocated addresses 000400₁₆ to 002BFF₁₆. Besides storing data, it becomes stacks when the subroutine is called or an interrupt is acknowledged.

SFR, consisting of control registers for peripheral functions such as I/O port, A/D conversion, serial I/O, and timers, is allocated addresses 000000₁₆ to 0003FF₁₆. All addresses, which have nothing allocated within SFR, are reserved space and cannot be accessed by users.

The special page vectors are allocated addresses FFFE00₁₆ to FFFFDB₁₆. It is used for the JMPS instruction and JSRS instruction. Refer to the Renesas publication **Software Manual** for details.

In memory expansion mode and microprocessor mode, some space are reserved and cannot be accessed by users.

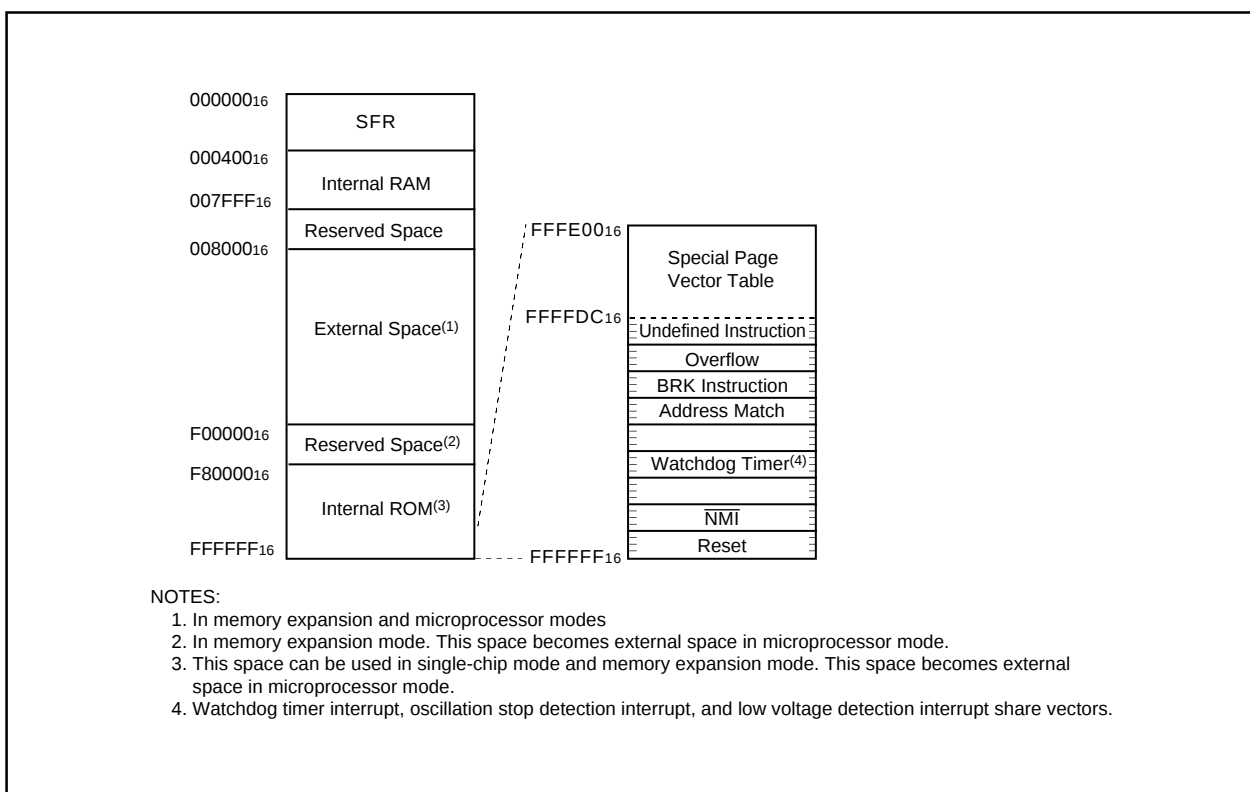


Figure 3.1 Memory Map

4. Special Function Registers (SFR)

Address	Register	Symbol	Value after RESET
0000 ₁₆			
0001 ₁₆			
0002 ₁₆			
0003 ₁₆			
0004 ₁₆	Processor Mode Register 0 ⁽¹⁾	PM0	1000 0000 ₂ (CNVss pin ="L") 0000 0011 ₂ (CNVss pin ="H")
0005 ₁₆	Processor Mode Register 1	PM1	0X00 0000 ₂
0006 ₁₆	System Clock Control Register 0	CM0	0000 X000 ₂
0007 ₁₆	System Clock Control Register 1	CM1	0010 0000 ₂
0008 ₁₆	Wait Control Register ⁽²⁾	WCR	1111 1111 ₂
0009 ₁₆	Address Match Interrupt Enable Register	AIER	XXXX 0000 ₂
000A ₁₆	Protect Register	PRCR	XXXX 0000 ₂
000B ₁₆	External Data Bus Width Control Register ⁽²⁾	DS	XXXX 1000 ₂ (BYTE pin ="L") XXXX 0000 ₂ (BYTE pin ="H")
000C ₁₆	Main Clock Division Register	MCD	XXX0 1000 ₂
000D ₁₆	Oscillation Stop Detection Register	CM2	00 ₁₆
000E ₁₆	Watchdog Timer Start Register	WDTS	XX ₁₆
000F ₁₆	Watchdog Timer Control Register	WDC	000X XXXX ₂
0010 ₁₆	Address Match Interrupt Register 0	RMAD0	00 00 00 ₁₆
0011 ₁₆			
0012 ₁₆			
0013 ₁₆			
0014 ₁₆	Address Match Interrupt Register 1	RMAD1	00 00 00 ₁₆
0015 ₁₆			
0016 ₁₆			
0017 ₁₆	VDC Control Register for PLL	PLV	XXXX XX01 ₂
0018 ₁₆	Address Match Interrupt Register 2	RMAD2	00 00 00 ₁₆
0019 ₁₆			
001A ₁₆			
001B ₁₆	VDC Control Register 0	VDC0	00 ₁₆
001C ₁₆	Address Match Interrupt Register 3	RMAD3	00 00 00 ₁₆
001D ₁₆			
001E ₁₆			
001F ₁₆			
0020 ₁₆			
0021 ₁₆			
0022 ₁₆			
0023 ₁₆			
0024 ₁₆			
0025 ₁₆			
0026 ₁₆			
0027 ₁₆			
0028 ₁₆			
0029 ₁₆			
002A ₁₆			
002B ₁₆			
002C ₁₆			
002D ₁₆			
002E ₁₆			
002F ₁₆			

X: Indeterminate

Blank spaces are reserved. No access is allowed.

NOTES:

1. The PM00 and PM01 bits in the PM1 register maintain values set before reset even if software reset or watchdog timer reset is performed.
2. These registers in M32C/83T cannot be used.

**Table 5.3 Electrical Characteristics (V_{CC}=4.2 to 5.5V, V_{SS}=0V
at T_{opr}= -20 to 85°C, f(X_{IN})=32MHz unless otherwise specified)**

Symbol	Parameter	Condition	Standard			Unit	
			Min	Typ	Max		
V _{OH}	Output High ("H") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OH} =-5mA	V _{CC} - 2.0		V	
		P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OH} =-200μA	V _{CC} - 0.3			
		X _{OUT}	I _{OH} =-1mA	3.0		V	
		X _{COU} T	No load applied		3.3	V	
V _{OL}	Output Low ("L") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OL} =5mA		2.0	V	
		P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OL} =200μA		0.45	V	
		X _{OUT}	I _{OL} =1mA		2.0	V	
		X _{COU} T	No load applied		0	V	
V _{T+} -V _{T-}	Hysteresis	HOLD, RDY, TA0IN-TA4IN, TB0IN-TB5IN, INT0-INT5, AD _{TRG} , CTS0-CTS4, CLK0-CLK4, TA0OUT-TA4OUT, NMI, KI0-KI3, RxD0-RxD4, SCL0-SCL4, SDA0-SDA4		0.2	1.0	V	
		RESET		0.2	1.8	V	
I _{IH}	Input High ("H") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	V _I =5V		5.0	μA	
I _{IL}	Input Low ("L") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	V _I =0V		-5.0	μA	
R _{PULLUP}	Pull-up Resistance	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	V _I =0V	30	50	167	kΩ
R _{FXIN}	Feedback Resistance	X _{IN}			1.5		MΩ
R _{FXQIN}	Feedback Resistance	X _{QIN}			10		MΩ
V _{RAM}	RAM Standby Voltage	Through VDC		2.5			V
I _{CC}	Power Supply Current	Measurement conditions: In single-chip mode, output pins are left open and other pins are connected to V _{SS} .	f(X _{IN})=32 MHz, square wave, no division		40	54	mA
			f(X _{QIN})=32 kHz, with a wait state, T _{opr} =25° C		470		μA
			T _{opr} =25° C when the clock stops		0.4	20	μA

NOTES:

1. P11 to P15 are provided in the 144-pin package only.

Switching Characteristics(V_{CC} = 4.2 to 5.5V, V_{SS} = 0V at T_{opr} = –20 to 85°C unless otherwise specified)**Table 5.22 Memory Expansion Mode and Microprocessor Mode
(With a Wait State, Accessing an External Memory and Selecting a Space with the Multiplexed Bus)**

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min	Max	
td(BCLK-AD)	Address Output Delay Time	See Figure 5.1		18	ns
th(BCLK-AD)	Address Output Hold Time (BCLK standard)		-3		ns
th(RD-AD)	Address Output Hold Time (RD standard)		(Note 1)		ns
th(WR-AD)	Address Output Hold Time (WR standard)		(Note 1)		ns
td(BCLK-CS)	Chip-select Signal Output Delay Time			18	ns
th(BCLK-CS)	Chip-select Signal Output Hold Time (BCLK standard)		-3		ns
th(RD-CS)	Chip-select Signal Output Hold Time (RD standard)		(Note 1)		ns
th(WR-CS)	Chip-select Signal Output Hold Time (WR standard)		(Note 1)		ns
td(BCLK-RD)	RD Signal Output Delay Time			18	ns
th(BCLK-AD)	RD Signal Output Hold Time		-5		ns
td(BCLK-WR)	WR Signal Output Delay Time			18	ns
th(BCLK-WR)	WR Signal Output Hold Time		-3		ns
td(DB-WR)	Data Output Delay Time (WR standard)		(Note 1)		ns
th(WR-DB)	Data Output Hold Time (WR standard)		(Note 1)		ns
td(BCLK-ALE)	ALE Signal Output Delay Time (BCLK standard)			18	ns
th(BCLK-ALE)	ALE Signal Output Hold Time (BCLK standard)		-2		ns
td(AD-ALE)	ALE Signal Output Delay Time (address standard)		(Note 1)		ns
th(ALE-AD)	ALE Signal Output Hold Time (address standard)		(Note 1)		ns
tdz(RD-AD)	Address Output High-Impedance Time			8	ns

NOTES:

1. Values can be obtained from the following equations, according to BCLK frequency.

$$th(RD - AD) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(WR - AD) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(RD - CS) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(WR - CS) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$td(DB - WR) = \frac{10^9 \times m}{f(BCLK) \times 2} - 25 \quad [ns] \quad (m=3 \text{ with 2 wait states and } m=5 \text{ with 3 wait states})$$

$$th(WR - DB) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$td(AD - ALE) = \frac{10^9}{f(BCLK) \times 2} - 20 \quad [ns]$$

$$th(ALE - AD) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

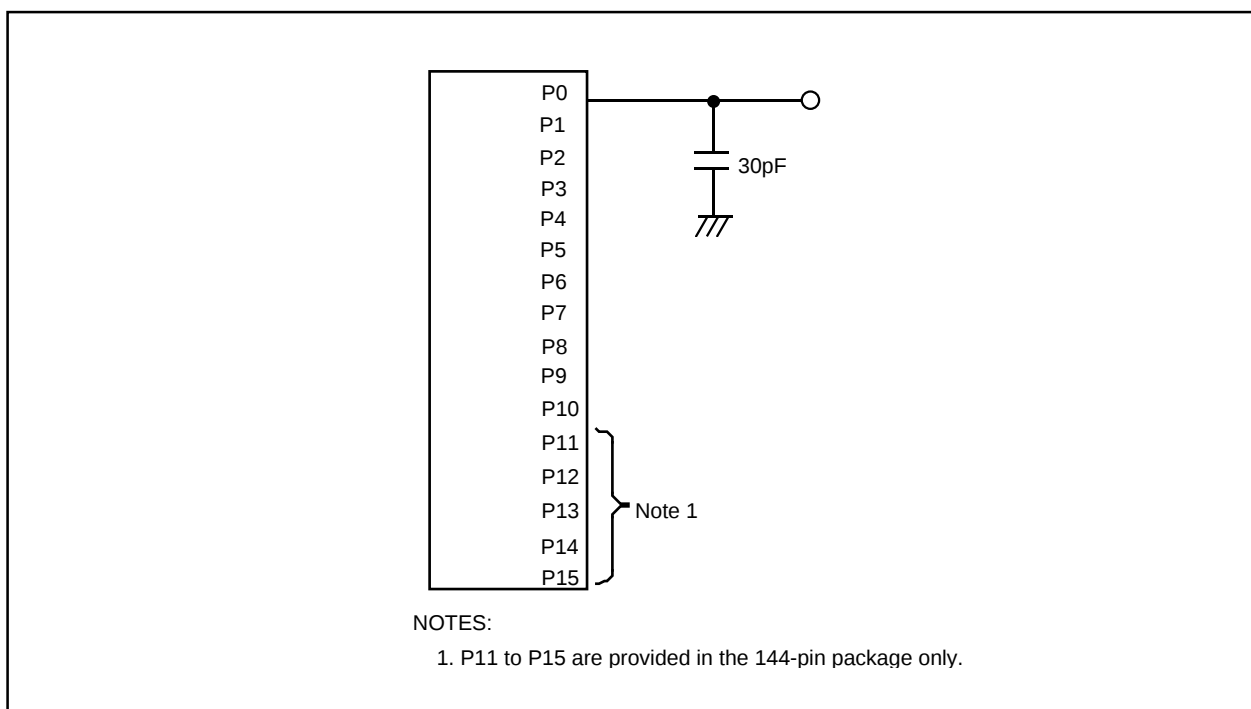
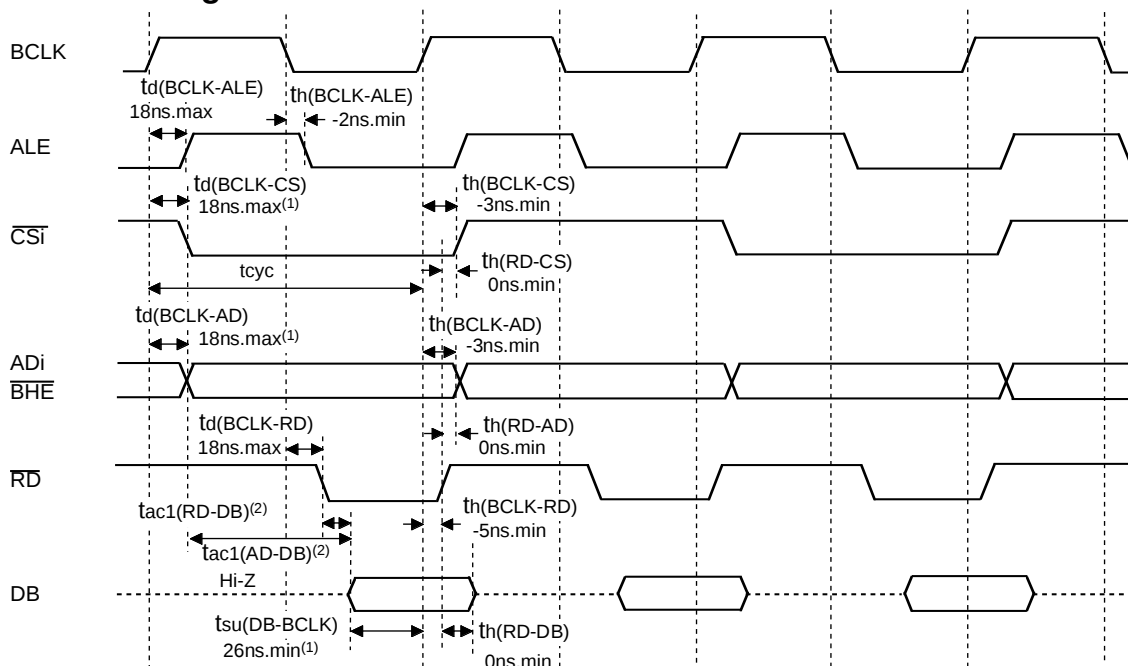


Figure 5.1 P0 to P15 Measurement Circuit

V_{CC}=5V

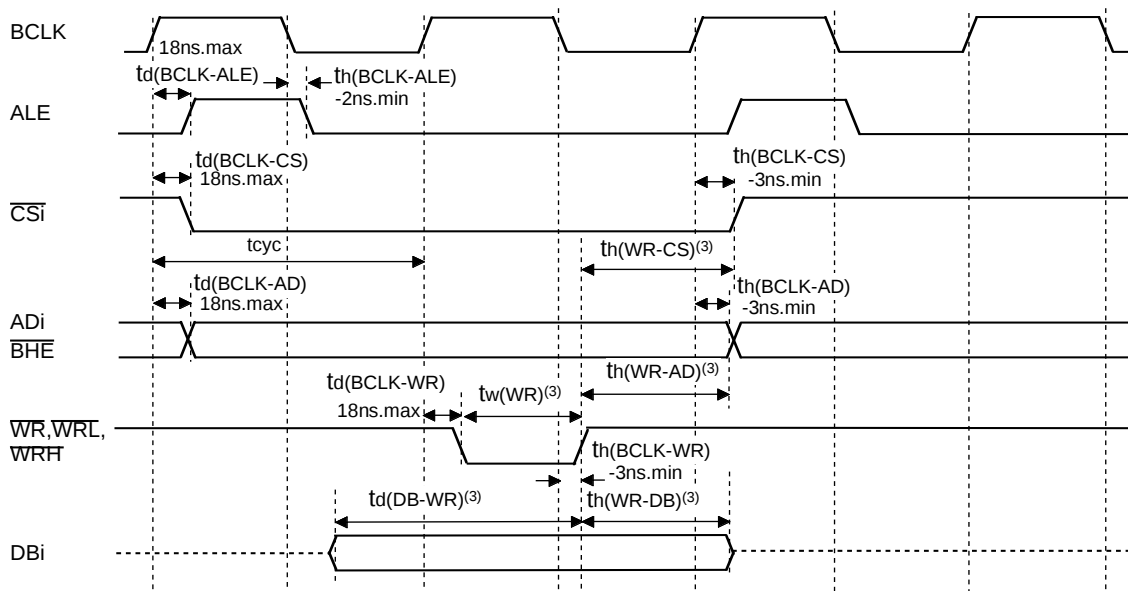
Memory Expansion Mode and Microprocessor Mode (with no wait state) Read Timing



NOTES:

- Values guaranteed only when the microcomputer is used independently.
A maximum of 35ns is guaranteed for $t_d(\text{BCLK-AD}) + t_{su}(\text{DB-BCLK})$.
- Varies with operation frequency:
 $t_{ac1}(\text{RD-DB}) = (t_{cyc}/2 - 35)\text{ns.max}$
 $t_{ac1}(\text{AD-DB}) = (t_{cyc} - 35)\text{ns.max}$

Write Timing (written in 2 cycles with no wait state)



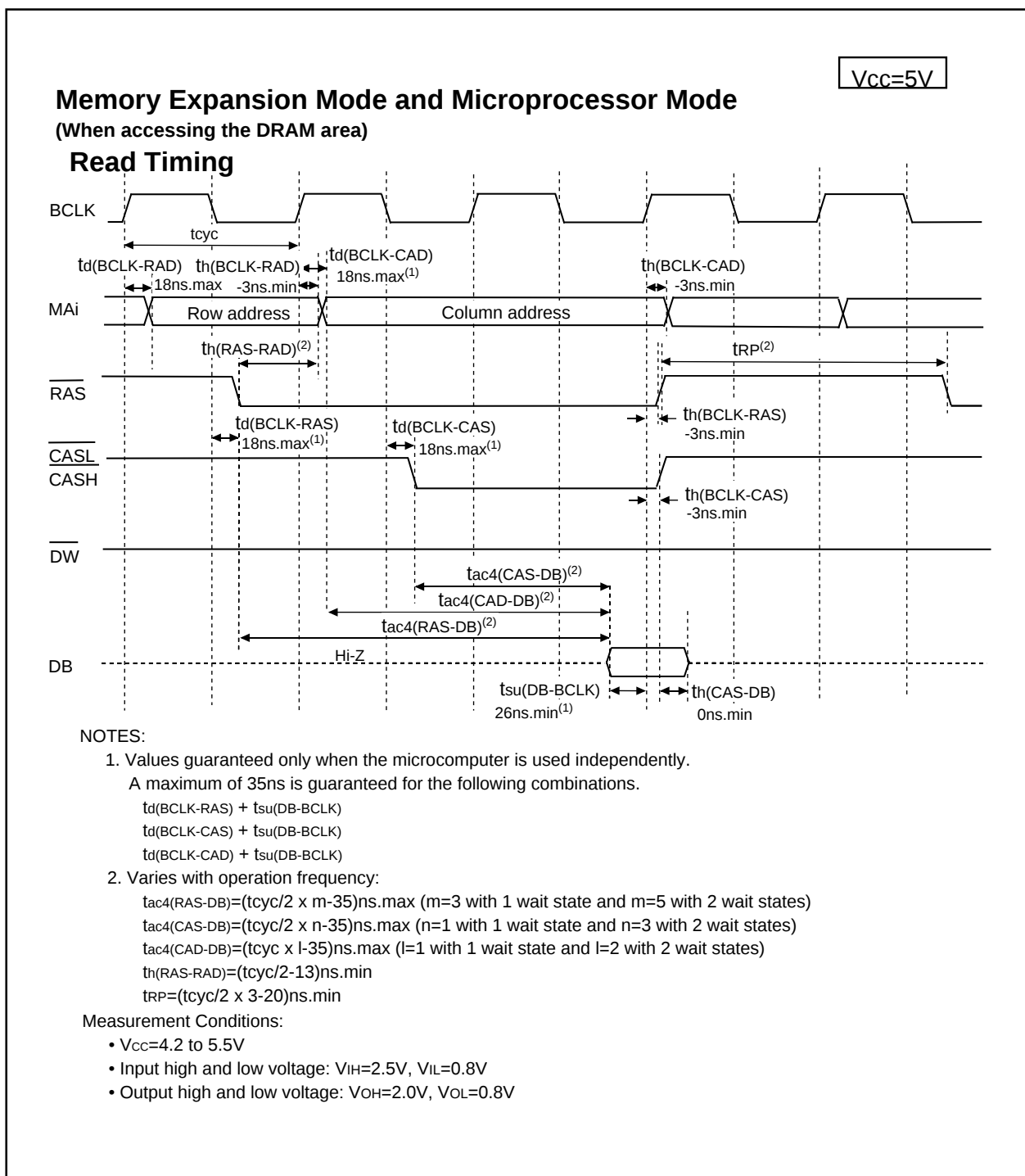
NOTES:

- Varies with operation frequency:
 $t_d(\text{DB-WR}) = (t_{cyc} - 20)\text{ns.min}$
 $t_h(\text{WR-DB}) = (t_{cyc}/2 - 10)\text{ns.min}$
 $t_h(\text{WR-AD}) = (t_{cyc}/2 - 10)\text{ns.min}$
 $t_h(\text{WR-CS}) = (t_{cyc}/2 - 10)\text{ns.min}$
 $t_w(\text{WR}) = (t_{cyc}/2 - 15)\text{ns.min}$

Measurement Conditions:

- V_{CC}=4.2 to 5.5V
- Input high and low voltage: V_{IH}=2.5V, V_{IL}=0.8V
- Output high and low voltage: V_{OH}=2.0V, V_{OL}=0.8V

Figure 5.2 V_{CC}=5V Timing Diagram (1)

Figure 5.5 V_{CC}=5V Timing Diagram (4)

**Table 5.24 Electrical Characteristics (V_{CC}=3.0 to 3.6V, V_{SS}=0V at T_{opr} = –20 to 85°C,
f(X_{IN})=20MHz unless otherwise specified)**

Symbol	Parameter		Condition	Standard			Unit
				Min	Typ	Max	
V _{OH}	Output High ("H") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OH} =-1mA	V _{CC} -0.6			V
		X _{OUT}	I _{OH} =-0.1mA	2.7			V
		X _{COUT}	No load applied		3.3		V
V _{OL}	Output Low ("L") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OL} =1mA			0.5	V
		X _{OUT}	I _{OL} =0.1mA			0.5	V
		X _{COUT}	No load applied		0		V
V _{T+} -V _{T-}	Hysteresis	HOLD, RDY, TA0 _{IN} -TA4 _{IN} , TB0 _{IN} -TB5 _{IN} , INT0-INT5, AD _{TRG} , CTS0-CTS4, CLK0-CLK4, TA0 _{OUT} -TA4 _{OUT} , NMI, KI0-KI3, RxD0-RxD4, SCL0-SCL4, SDA0-SDA4		0.2		1.0	V
		RESET		0.2		1.8	V
I _{IH}	Input High ("H") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	V _I =3V			4.0	μA
I _{IL}	Input Low ("L") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	V _I =0V			-4.0	μA
R _{PULLUP}	Pull-up Resistance	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	V _I =0V	66	120	500	kΩ
R _{fXIN}	Feedback Resistance	X _{IN}			3.0		MΩ
R _{fXCIN}	Feedback Resistance	X _{CIN}			20.0		MΩ
V _{RAM}	RAM Standby Voltage	Through VDC		2.5			V
		Not through VDC		2.0			V
I _{CC}	Power Supply Current	Measurement condition: In single-chip mode, output pins are left open and other pins are connected to V _{SS} .	f(X _{IN})=20 MHz, square wave, no division		26	38	mA
			f(X _{CIN})=32 kHz, with a wait state, not through VDC, T _{opr} =25° C		5.0		μA
			f(X _{CIN})=32 kHz, with a wait state, through VDC, T _{opr} =25° C		340		μA
			T _{opr} =25° C when the clock stops		0.4	20	μA

NOTES:

1. P11 to P15 are provided in the 144-pin package only.

Switching Characteristics(V_{CC} = 3.0 to 3.6V, V_{SS} = 0V at Topr = –20 to 85°C unless otherwise specified)**Table 5.44 Memory Expansion Mode and Microprocessor Mode
(With a Wait State, Accessing an External Memory and Selecting the DRAM Area)**

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min	Max	
td(BCLK-RAD)	Row Address Output Delay Time	See Figure 5.1		18	ns
th(BCLK-RAD)	Row Address Output Hold Time (BCLK standard)		0		ns
td(BCLK-CAD)	Column Address Output Delay Time			18	ns
th(BCLK-CAD)	Column Address Output Hold Time (BCLK standard)		0		ns
th(RAS-RAD)	Row Address Output Hold Time after RAS Output		(Note 1)		ns
td(BCLK-RAS)	RAS Output Delay Time (BCLK standard)			18	ns
th(BCLK-RAS)	RAS Output Hold Time (BCLK standard)		0		ns
trp	RAS High ("H") Hold Time		(Note 1)		ns
td(BCLK-CAS)	CAS Output Delay Time (BCLK standard)			18	ns
th(BCLK-CAS)	CAS Output Hold Time (BCLK standard)		0		ns
td(BCLK-DW)	DW Output Delay Time (BCLK standard)			18	ns
th(BCLK-DW)	DW Output Hold Time (BCLK standard)		-3		ns
tsu(DB-CAS)	CAS Output Setup Time after DB output		(Note 1)		ns
th(BCLK-DB)	DB Signal Output Hold Time (BCLK standard)		-7		ns
tsu(CAS-RAS)	CAS Output Setup Time before RAS Output (refresh)		(Note 1)		ns

NOTES:

1. Values can be obtained from the following equations, according to the BCLK frequency.

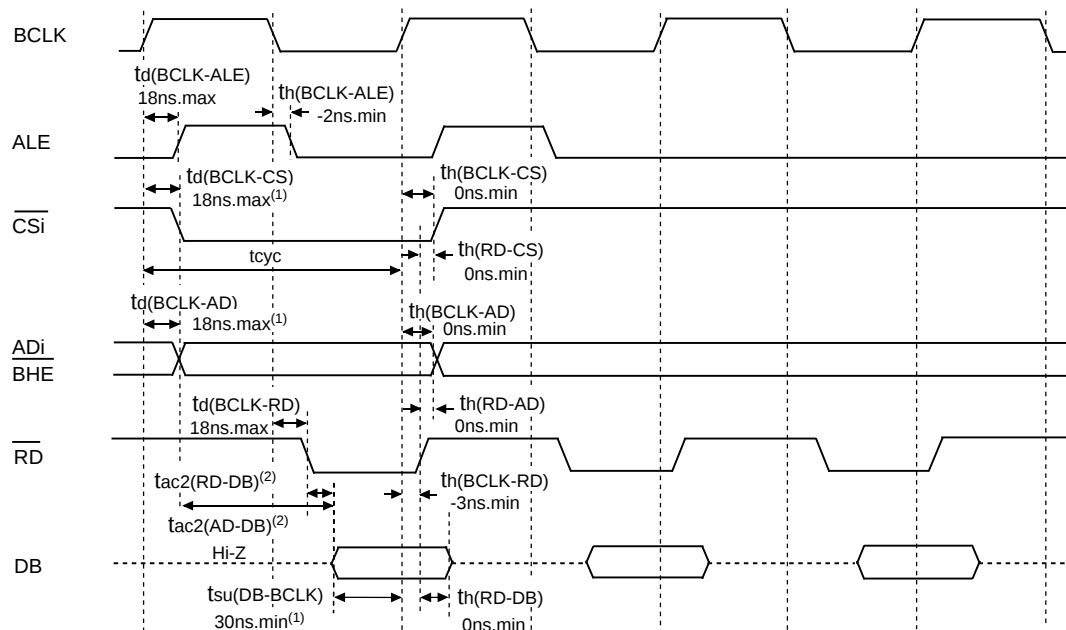
$$th(RAS - RAD) = \frac{10^9}{f(BCLK) \times 2} - 13 \quad [ns]$$

$$trp = \frac{10^9 \times 3}{f(BCLK) \times 2} - 20 \quad [ns]$$

$$tsu(DB - CAS) = \frac{10^9}{f(BCLK)} - 20 \quad [ns]$$

$$tsu(CAS - RAS) = \frac{10^9}{f(BCLK) \times 2} - 13 \quad [ns]$$

Memory Expansion Mode and Microprocessor Mode (with no wait state) Read Timing



NOTES:

1. Values guaranteed only when the microcomputer is used independently.

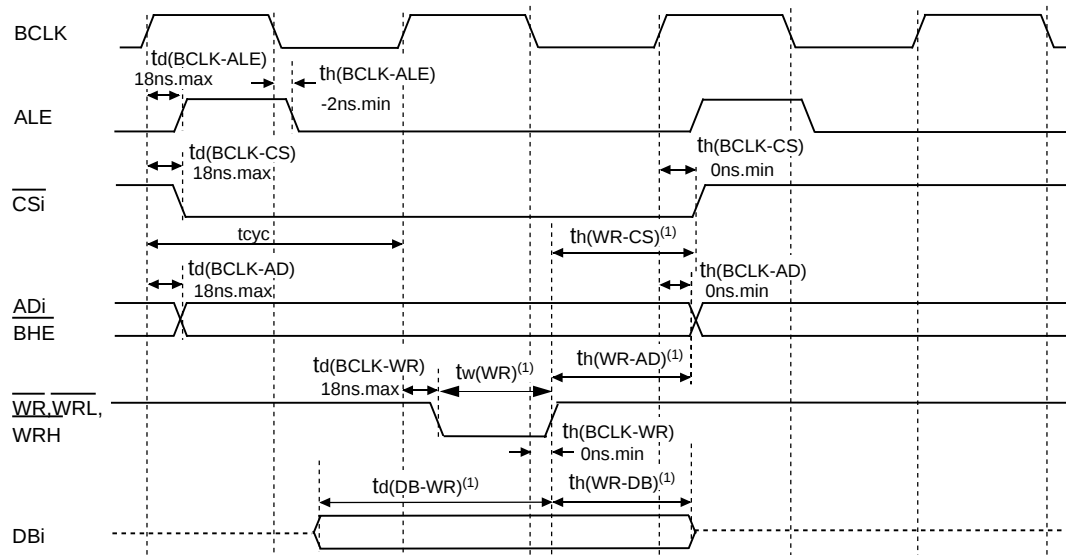
A maximum of 35ns is guaranteed for $t_d(\text{BCLK-AD}) + t_{su}(\text{DB-BCLK})$.

2. Varies with operation frequency:

$$t_{ac2}(\text{RD-DB}) = (t_{cyc}/2 - 35)\text{ns.max}$$

$$t_{ac2}(\text{AD-DB}) = (t_{cyc} - 35)\text{ns.max}$$

Write Timing



NOTES:

1. Varies with operation frequency.

$$t_d(\text{DB-WR}) = (t_{cyc} - 20)\text{ns.min}$$

$$t_h(\text{WR-DB}) = (t_{cyc}/2 - 10)\text{ns.min}$$

$$t_h(\text{WR-AD}) = (t_{cyc}/2 - 10)\text{ns.min}$$

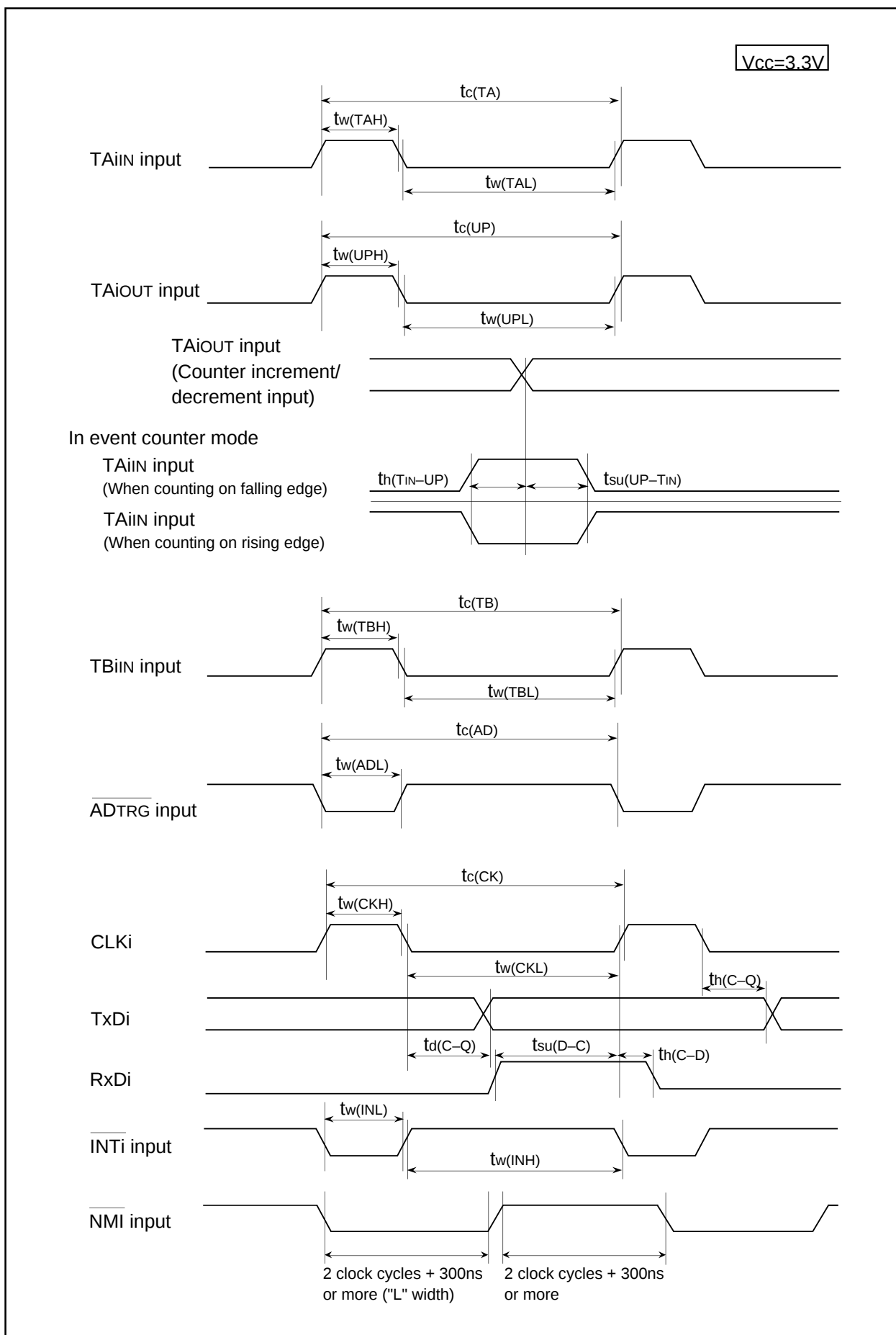
$$t_h(\text{WR-CS}) = (t_{cyc}/2 - 10)\text{ns.min}$$

$$t_w(\text{WR}) = (t_{cyc}/2 - 15)\text{ns.min}$$

Measurement Conditions:

- V_{CC}=3.0 to 3.6V
- Input high and low voltage: V_{IH}=1.5V, V_{IL}=0.5V
- Output high and low voltage: V_{OH}=1.5V, V_{OL}=1.5V

Figure 5.10 V_{CC}=3.3V Timing Diagram (1)

Figure 5.16 $V_{CC}=3.3V$ Timing Diagram (7)

5.2 Electrical Characteristics (M32C/83T)

Table 5.45 Absolute Maximum Ratings

Symbol	Parameter		Condition	Value	Unit
V _{CC}	Supply Voltage		V _{CC} =AV _{CC}	-0.3 to 6.0	V
AV _{CC}	Analog Supply Voltage		V _{CC} =AV _{CC}	-0.3 to 6.0	V
V _I	Input Voltage	RESET, CNV _{SS} , BYTE, P0 ₀ -P0 ₇ , P1 ₀ -P1 ₇ , P2 ₀ -P2 ₇ , P3 ₀ -P3 ₇ , P4 ₀ -P4 ₇ , P5 ₀ -P5 ₇ , P6 ₀ -P6 ₇ , P7 ₂ -P7 ₇ , P8 ₀ -P8 ₇ , P9 ₀ -P9 ₇ , P10 ₀ -P10 ₇ , P11 ₀ -P11 ₄ , P12 ₀ -P12 ₇ , P13 ₀ -P13 ₇ , P14 ₀ -P14 ₆ , P15 ₀ -P15 ₇ ⁽¹⁾ , V _{REF} , X _{IN}		-0.3 to V _{CC} +0.3	V
		P7 ₀ , P7 ₁		-0.3 to 6.0	V
V _O	Output Voltage	P0 ₀ -P0 ₇ , P1 ₀ -P1 ₇ , P2 ₀ -P2 ₇ , P3 ₀ -P3 ₇ , P4 ₀ -P4 ₇ , P5 ₀ -P5 ₇ , P6 ₀ -P6 ₇ , P7 ₂ -P7 ₇ , P8 ₀ -P8 ₄ , P8 ₆ , P8 ₇ , P9 ₀ -P9 ₇ , P10 ₀ -P10 ₇ , P11 ₀ -P11 ₄ , P12 ₀ -P12 ₇ , P13 ₀ -P13 ₇ , P14 ₀ -P14 ₆ , P15 ₀ -P15 ₇ ⁽¹⁾ , X _{OUT}		-0.3 to V _{CC} +0.3	V
P _d	Power Dissipation		T _{opr} =25° C	400	mW
T _{opr}	Operating Ambient Temperature		T version	-40 to 85	° C
T _{stg}	Storage Temperature			-65 to 150	° C

NOTES:

1. P11 to P15 are provided in the 144-pin package.

Table 5.46 Recommended Operating Conditions**(V_{CC}=4.2 to 5.5V, V_{SS}=0V at T_{opr} = -40 to 85°C (T version) unless otherwise specified)**

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
V _{CC}	Supply Voltage		4.2	5.0	5.5	V
AV _{CC}	Analog Supply Voltage			V _{CC}		V
V _{SS}	Supply Voltage			0		V
AV _{SS}	Analog Supply Voltage			0		V
V _{IH}	Input High ("H") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P87 ⁽³⁾ , P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	0.8V _{CC}		V _{CC}	V
		P70, P71	0.8V _{CC}		6.0	
V _{IL}	Input Low ("L") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87 ⁽³⁾ , P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	0		0.2V _{CC}	V
I _{OH(peak)}	Peak Output High ("H") Current ⁽²⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾			-10.0	mA
I _{OH(avg)}	Average Output High ("H") Current ⁽¹⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾			-5.0	mA
I _{OL(peak)}	Peak Output Low ("L") Current ⁽²⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾			10.0	mA
I _{OL(avg)}	Average Output Low ("L") Current ⁽¹⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾			5.0	mA
f(X _{IN})	Main Clock Input Frequency	V _{CC} =4.2 to 5.5V	0		32	MHz
f(X _{CIN})	Sub Clock Oscillation Frequency			32.768	50	kHz

NOTES:

- Typical values when average output current is 100ms.
- Total I_{OL(peak)} for P0, P1, P2, P86, P87, P9, P10, P11, P14 and P15 must be 80mA or less.
Total I_{OH(peak)} for P0, P1, P2, P86, P87, P9, P10, P11, P14 and P15 must be -80mA or less.
Total I_{OL(peak)} for P3, P4, P5, P6, P7, P80 to P84, P12 and P13 must be 80mA or less.
Total I_{OH(peak)} for P3, P4, P5, P6, P72 to P77, P80 to P84, P12 and P13 must be -80mA or less.
- V_{IH} and V_{IL} reference for P87 applies when P87 is used as a programmable input port.
It does not apply when P87 is used as X_{CIN}.
- P11 to P15 are provided in the 144-pin package only.

REVISION HISTORY

M32C/83 GROUP (M32C/83, M32C/83T) Datasheet

Rev.	Date	Description	
		Page	Summary
1.10	2003-9	-	New Document
1.20	2003-12		Maximum operating frequency changed from 30 MHz to 32 MHz. Overview, Electrical Characteristics Table 1.1 M32C/83 Group Performance (144-Pin Package) Table 1.2 M32C/83 Group Performance (100-Pin Package) Table 5.2 Recommended Operating Conditions Table 5.3 Electrical Characteristics
1.30	2004-06	All pages	Words standardized: On-chip oscillator, A/D converter and D/A converter
1.41	2006-01	All Pages	M32C/83T version added; Package code changed: 144P6Q-A to PLQP0144KA-A, 100P6Q-A to PLQP0100KB-A, 100P6S-A to PRQP0100JB-A
		All Pages	Word standardized: Clock Generation Circuit , On-chip Oscillator, A/D Converter, D/A Converter, XY Conversion, Low -power consumption
		1 2, 3 5	Overview • 1.1 Applications Automobile added • Tables 1.1 and 1.2 M32C/83 Group (M32C/83, M32C/83T) Performance • Table 1.3 M32C/83 Group (1) (M32C/83) Information updated • Table 1.3 M32C/83 Group (2) (M32C/83T) M32C/83T product information added • Figure 1.2 Product Numbering System Classification modified • Table 1.4 Pin Characteristics for 144-Pin Package Note 1 added • Table 1.5 Pin Characteristics for 100-Pin Package Note 1 added • Table 1.6 Pin Description modified, notes added
		21	Memory • Figure 3.1 Memory Map modified; Note 2 modified, notes 3 and 4 added
		22 to 23	Special Function Registers (SFR) • Note 2 added
		45	Reset • Figure 5.2 Reset Sequence Note 2 added
		46 54 62 64	Electrical Characteristics • Table 5.3 Electrical Characteristics Minimum standard values for V_{OH} revised, values for I_{CC} when f(X_{IN})=32 MHz, square wave, no division revised, one condition of "f(X_{IN})=32 MHz, square wave, no division" deleted • Table 5.23 Memory Expansion Mode and Microprocessor Mode Symbols for Row Address Output Delay Time and for Row Address Output Hold Time (BCLK standard) modified • Figure 5.8 V_{CC}=5 V Timing Diagram (7) Timing for $\overline{\text{NMI}}$ input added • Table 5.24 Electrical Characteristics Minimum standard value for V_{OH} revised